



#11/Amatt C
Atty. Docket No. 8013-1074
O'Neil

PATENTS
4/1/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Hidemitsu AOKI et al.

Confirmation No. 596

Serial No. 09/715,000

GROUP 2825

Filed November 20, 2000

Examiner Chuong A. Luu

IMPROVED SEMICONDUCTOR WAFER SURFACE
AND METHOD OF TREATING A SEMICONDUCTOR
WAFER SURFACE

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AMENDMENT

Commissioner for Patents

Washington, D.C. 20231

Sir:

Responsive to the Official Action of October 30, 2002,
please amend the above-identified application as follows:

IN THE CLAIMS:

Amend claim 1 as follows:

July 21
C1
--1. (twice amended) A method of treating a surface of
a semiconductor substrate, said surface of said semiconductor
substrate including at least any one of a copper region, a copper
based region and a copper alloy region, said method comprising
the steps of:

removing metal contaminations from said surface and
simultaneously or subsequently carrying out an anti-corrosion
treatment by exposing said surface of said semiconductor
substrate to a solution containing an anti-corrosive agent; and